

SMD ■ Side View LEDs (Height 0.6mm) 99-216/B7C-AS1T2N/2C



Features

- Side view blue LED.
- Lead frame package with individual 2 pins.
- Wide viewing angle.
- Soldering methods: IR reflow soldering.
- ESD protection.
- Pb-free.
- The product itself will remain within RoHS compliant version.

Descriptions

The 99-216 series is available in soft orange, green, blue and yellow. Due to the package design, the LED has wide viewing angle and optimized light coupling by inter reflector. This feature makes the LED ideal for light guide application.

Applications

- LCD Back Light.
- Mobile phones.
- Indicators.
- Illuminations.
- Switch Lights.

Device Selection Guide

Chip Materials	Emitted Color	Resin Color
InGaN	Blue	Water Clear

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	30	mA
Peak Forward Current (Duty 1/10 @1KHz)	I_{FP}	100	mA
Power Dissipation	P_d	110	mW
Junction Temperature	T_j	125	°C
Operating Temperature	T_{opr}	-40 ~ +100	°C
Storage Temperature	T_{stg}	-40 ~ +110	°C
Thermal Resistance	$R_{th\ J-A}$	600	K/W
	$R_{th\ J-S}$	400	K/W
ESD	ESD_{HBM}	2000	V
(Classification acc. AEC Q101)	ESD_{MM}	200	V
Soldering Temperature	T_{sol}	Reflow Soldering : 260 °C for 30 sec. Hand Soldering : 350 °C for 3 sec.	

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	I _v	180	-----	450	mcd	I _F =20mA
Viewing Angle	2θ _{1/2}	-----	120	-----	deg	I _F =20mA
Peak Wavelength	λ _p	-----	468	-----	nm	I _F =20mA
Dominant Wavelength	λ _d	464.5	----	476.5	nm	I _F =20mA
Spectrum Radiation Bandwidth	Δλ	-----	35	-----	nm	I _F =20mA
Forward Voltage	V _F	2.7	----	3.7	V	I _F =20mA
Reverse Current	I _R	-----	-----	10	μA	V _R =5V

Note:

1. Tolerance of Luminous Intensity: ±11%
2. Tolerance of Dominant Wavelength: ±1nm
3. Tolerance of Forward Voltage: ±0.1V

Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
S1	180	225	mcd	I _F =20mA
S2	225	285		
T1	285	360		
T2	360	450		

Note:

Tolerance of Luminous Intensity: ±11%

Bin Range of Dominant Wavelength

Bin Code	Min.	Max.	Unit	Condition
A9	464.5	467.5	nm	I _F =20mA
A10	467.5	470.5		
A11	470.5	473.5		
A12	473.5	476.5		

Note:

Tolerance of Dominant Wavelength: ±1nm

Bin Range of Forward Voltage

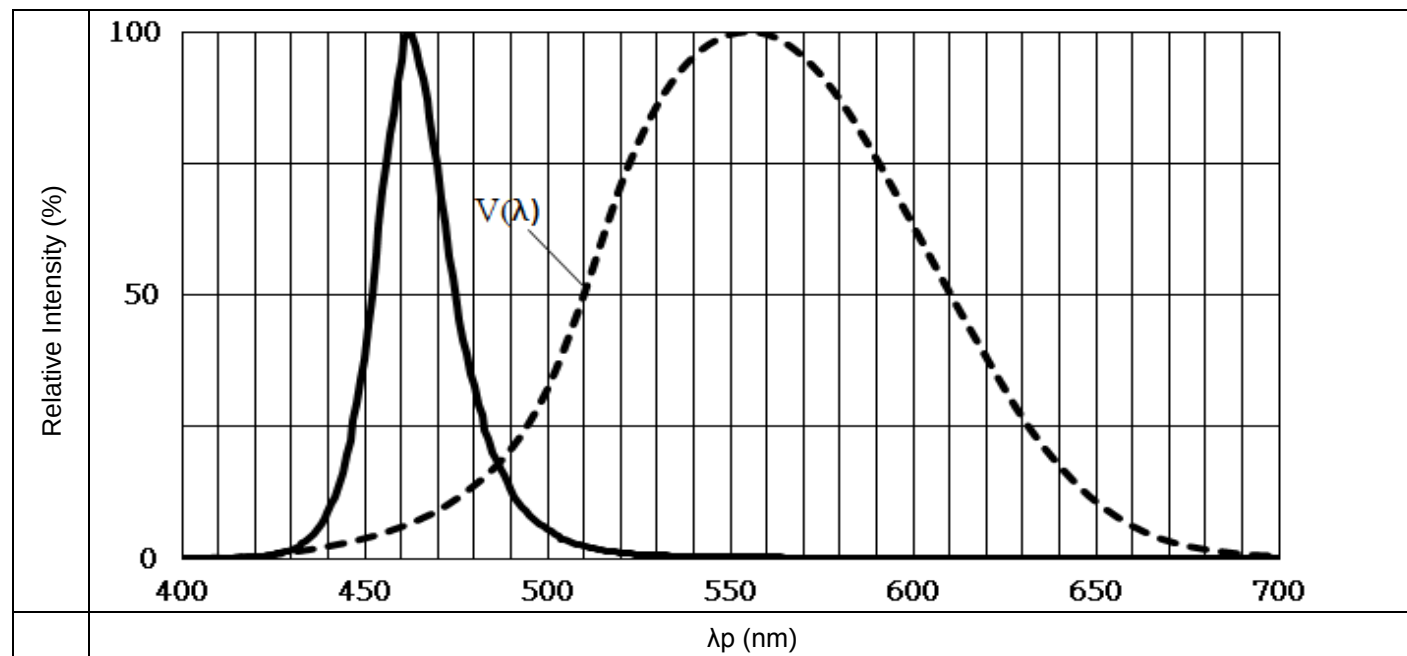
Bin Code	Min.	Max.	Unit	Condition
10	2.70	2.90	V	$I_F = 20\text{mA}$
11	2.90	3.10		
12	3.10	3.30		
13	3.30	3.50		
14	3.50	3.70		

Note:

Tolerance of Forward Voltage: $\pm 1\text{V}$

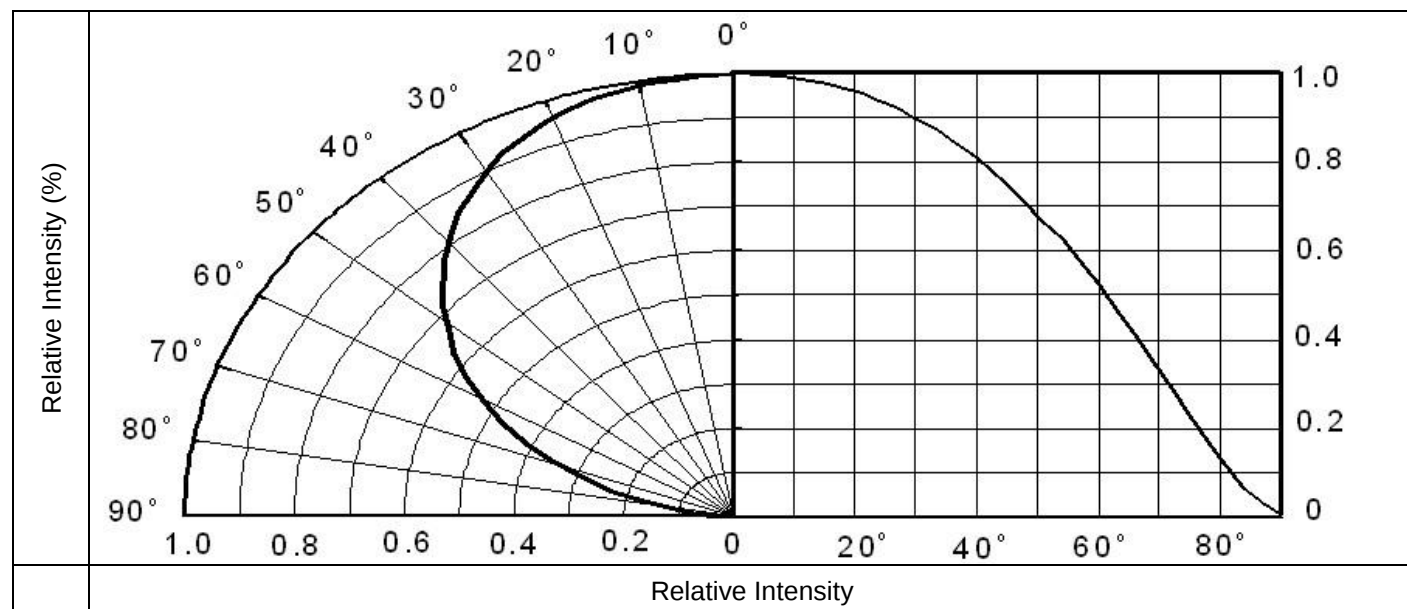
Typical Electro-Optical Characteristics Curves

Typical Curve of Spectral Distribution

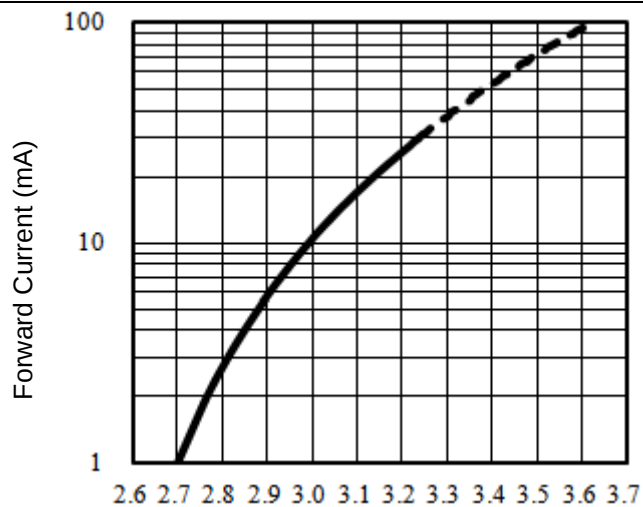


Note: $V(\lambda)$ =Standard eye response curve; $I_F = 20\text{mA}$

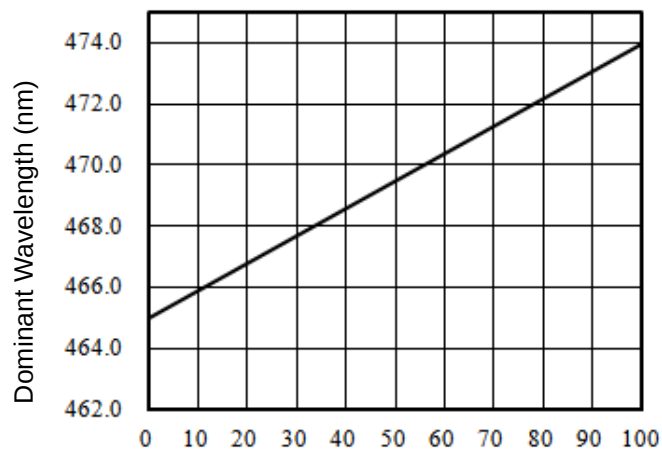
Diagram Characteristics of Radiation



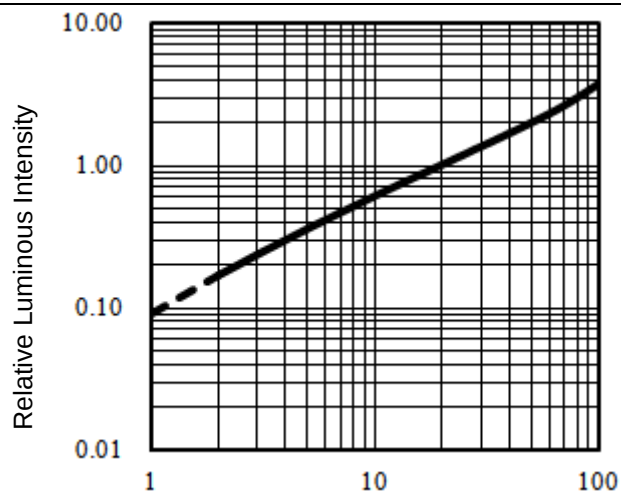
Forward Current vs. Forward Voltage (Ta=25°C)



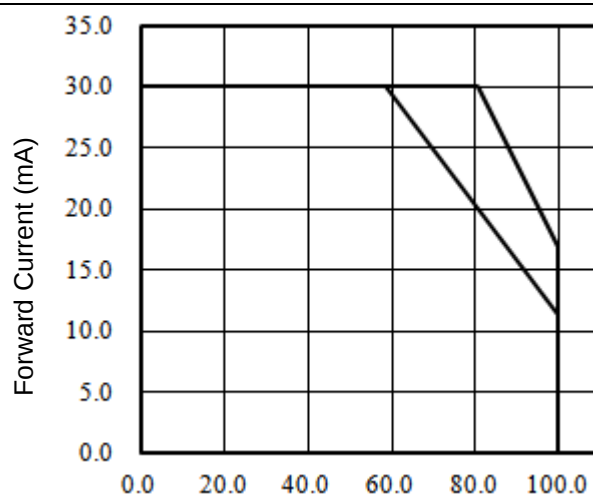
Dominant Wavelength vs. Forward Current (Ta=25°C)



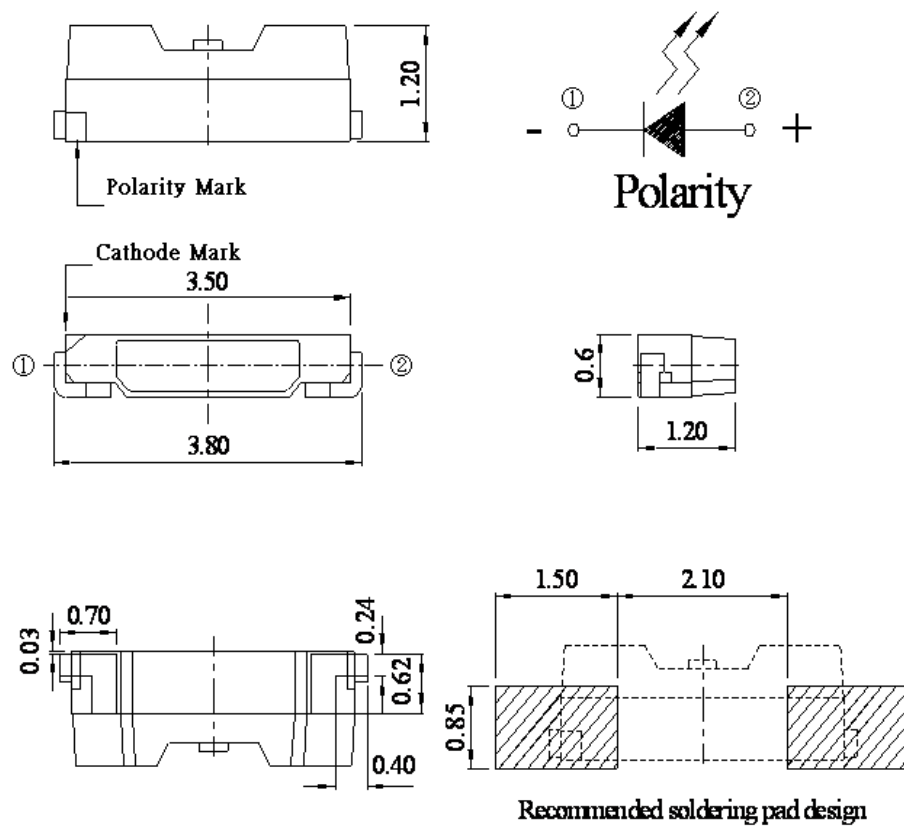
Relative Luminous Intensity vs. Forward Current (Ta=25°C)



Max. Permissible Forwarded Current (Ta=25°C)



Package Dimension



Note: Tolerances unless mentioned ± 0.1 mm. Unit = mm

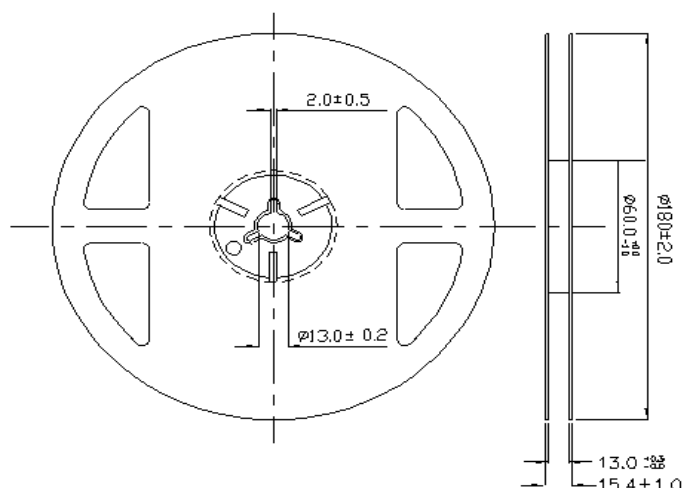
Moisture Resistant Packing Materials

Label Explanation

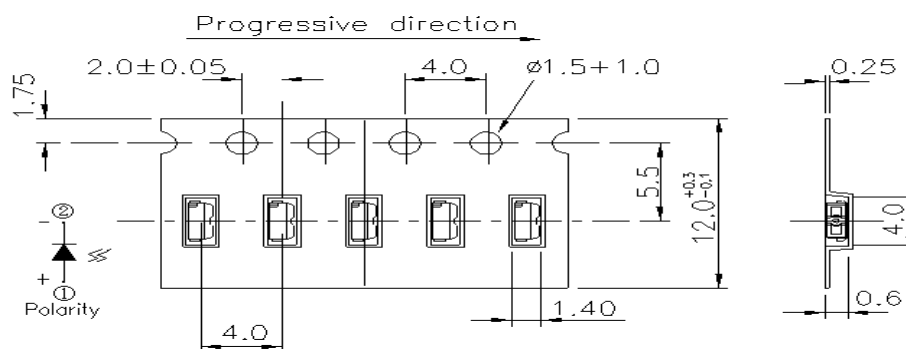


- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Dom. Wavelength Rank
- REF: Forward Voltage Rank
- LOT No: Lot Number

Reel Dimensions

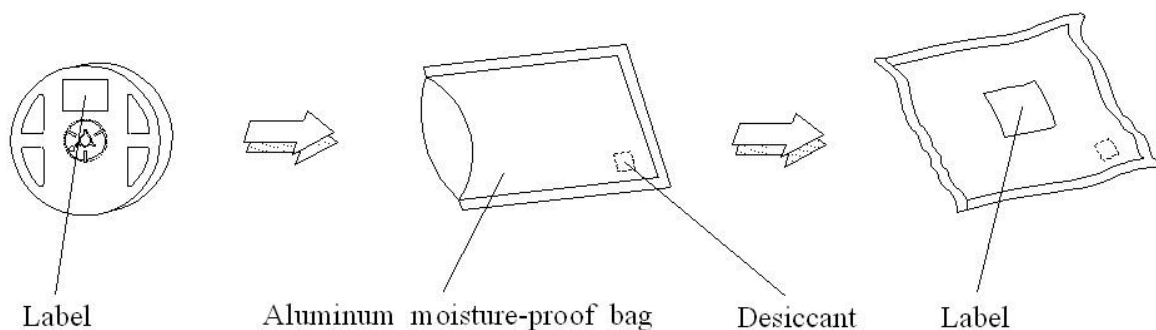


Carrier Tape Dimensions; Loaded Quantity 250 up/500/1000/2000 pcs Per Reel



Note: Tolerances unless mentioned ±0.1mm. Unit = mm

Moisture Resistant Packing Process

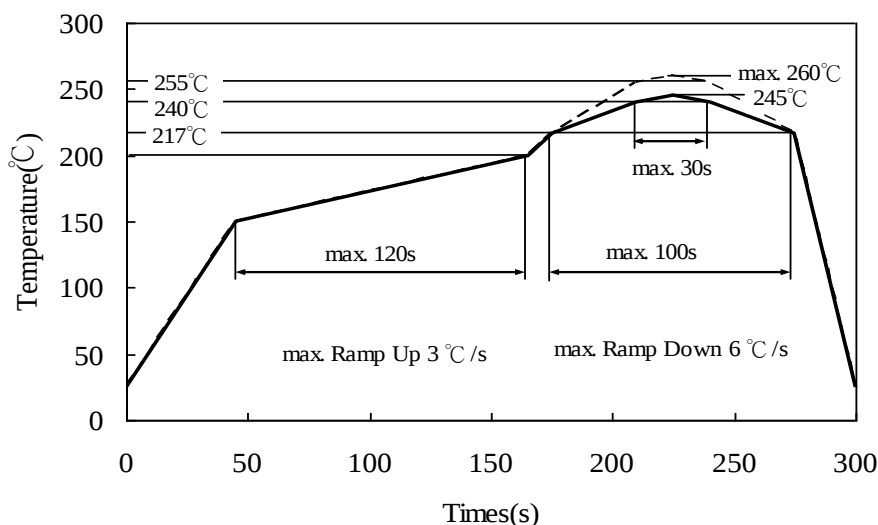


Note: Tolerances unless mentioned $\pm 0.1\text{mm}$. Unit = mm

Precautions for Use

1. Soldering Condition (Reference: IPC/JEDEC J-STD-020D)

1.1 Maximum Body Case Temperature Profile for evaluation of Reflow Profile



2. Current limiting

A resistor should be used to limit current spikes that can be caused by voltage fluctuations. Otherwise damage could occur.

3. Storage

- 3.1 Moisture proof bag should only be opened immediately prior to usage.
- 3.2 Environment should be less than 30°C and 60% RH when moisture proof bag is opened.
- 3.3 After opening the package MSL Conditions stated on page 1 of this spec should not be exceeded.
- 3.4 If the moisture sensitivity card indicates higher than acceptable moisture, the component should be baked at min. 60deg +/-5deg for 24 hours.

4. Iron Soldering

Hand soldering is not recommended for regular production. These guidelines are for rework only. Soldering iron tip should contact each terminal no more than 3 sec at 350°C, using soldering iron with nominal power less than 25W.

Allow min. 2 sec. between soldering intervals.

5. Usage

Do not exceed the values given in this specification.

Application Restrictions

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlight before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.

Revision History

Rev.	Modified date	File modified contents
1	2008/10/22	New Spec
2	2013/07/02	Change the new template